

REV	MODIFICATION	DATE	DRAW
A0	Release To ECN20140709	2014.07.31	Michelle

**RoHS Compliant**

**Specification**

- 1.Current Rating:1A AC/DC
- 2.Voltage Rating:200V AC/DC
- 3.Contact Resistance:20mΩ Max.
- 4.Insulation Resistance:100MΩ Min.
- 5.Withstand Voltage:AC500V/Minute
- 6.Operating Temperature:-25°C~+85°C

**Material:**

- 1.Housing:High Temperature Thermoplastic UL94V-0
- 2.Contact:Copper Alloy SQ. Pin 0.30mm
- 3.Tab:Copper Alloy T=0.20mm

**Finish:**

- 1.Housing:Natural
- 2.Contact:Bright Tin Plated
- 3.Tab:Tin Plated

Part No.: AS07901 02 X 1 X 1

Number of Pin  
02

Packing  
1:T&R  
4:Tube


**Housing Material**

- 3:PA46 UL94V-0 Natural
- 5:NY6T UL94V-0 Natural

**Plating**

1:Bright Tin Plated Over Nickel





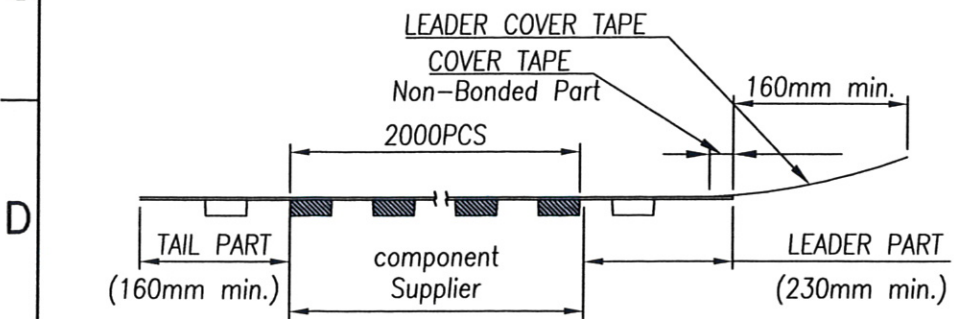
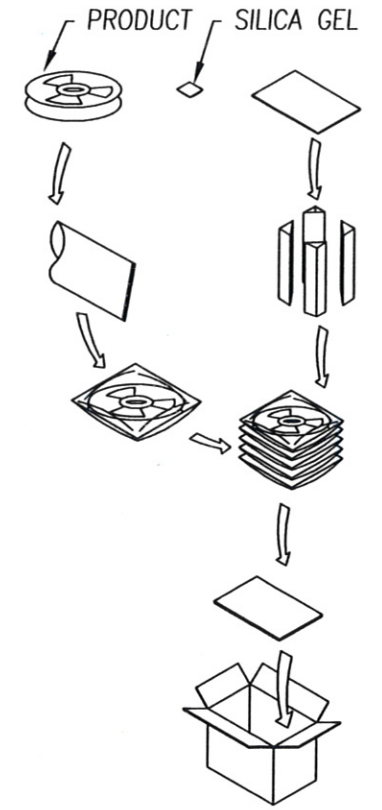
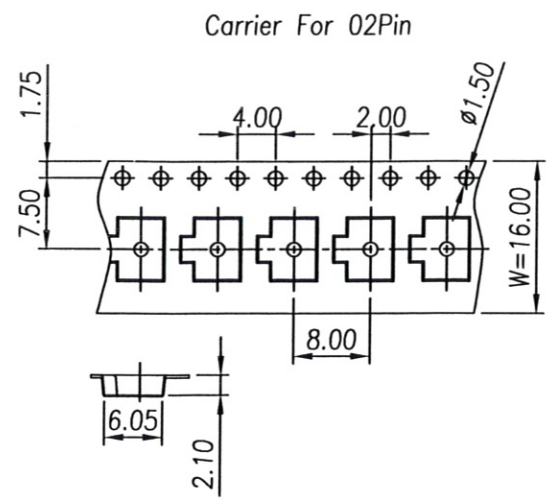
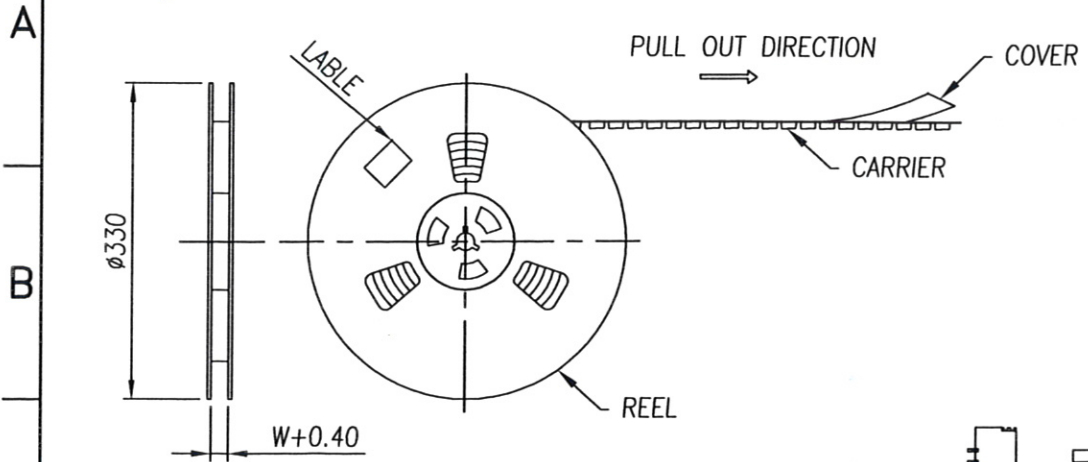
## 金上達科技股份有限公司

**GOLDENSUND TECHNOLOGY CO.,LTD**

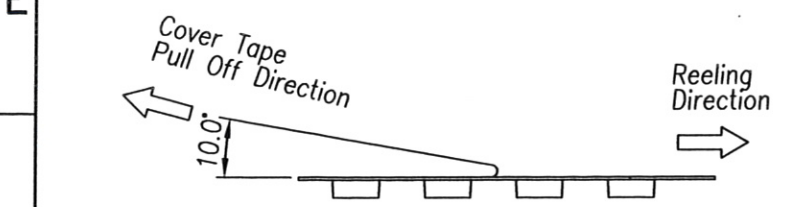
TOLERANCE UNLESS OTHERWISE SPECIFIED		PROJ.	TITLE: Wire To Board Wafer 1.25mm 90° SMT Single Row		
.X± 0.35	X.± 2'	APR. C.F.Liao 20140731	PART NO. AS0790102X1X1	DWG NO. AS0790102X1X1	
.XX± 0.25	.X'± 1'	CHK. Abel 20140731	UNITS: mm	CUSTOMER DRAWING	
.XXX± 0.15	.XX'± 0.5'	DRA. Michelle 20140731	SIZE: <b>A4</b>	SCALE 10:1	SHEET 1 / 2
			REV A0		

RoHS Compliant

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- Notes:
1. Material : PS
  2. Part No.: AS0790102X111



發行  
103. 7. 31  
文管中心

		<b>金上達科技股份有限公司</b> <b>GOLDENSUND TECHNOLOGY CO.,LTD</b>	
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SIZE: <b>A4</b>		SCALE Free	
SHEET 2 / 2		REV A0	

CUSTOMER DRAWING